

# HSB226WK

# Silicon Schottky Barrier Diode for High Speed Switching

REJ03G0592-0200 Rev.2.00 Sep 15, 2006

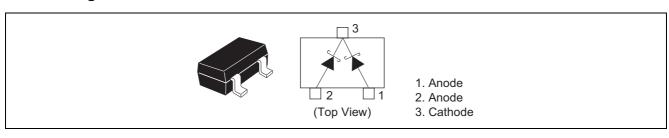
#### **Features**

- Low reverse current, Low capacitance.
- CMPAK package is suitable for high density surface mounting and high speed assembly.

## **Ordering Information**

Type No.	Laser Mark	Package Name	Package Code
HSB226WK	E6	CMPAK	PTSP0003ZB-A

### **Pin Arrangement**



# **Absolute Maximum Ratings**

 $(Ta = 25^{\circ}C)$ 

Item	Symbol	Value	Unit
Repetitive peak reverse voltage	$V_{RRM}$	25	V
Non-Repetitive peak forward surge current	I <sub>FSM</sub> *1 *2	200	mA
Forward current	I <sub>F</sub> * <sup>2</sup>	50	mA
Junction temperature	Tj	125	°C
Storage temperature	Tstg	-55 to +125	°C

Notes: 1. 10 ms sine wave 1 pulse

2. Two device total

#### **Electrical Characteristics \***

 $(Ta = 25^{\circ}C)$ 

Item	Symbol	Min	Тур	Max	Unit	Test Condition
Forward voltage	V <sub>F1</sub>	-	-	0.33	V	$I_F = 1 \text{ mA}$
	$V_{F2}$	-	_	0.38		$I_F = 5 \text{ mA}$
Reverse current	I <sub>R</sub>	_	_	450	nA	V <sub>R</sub> = 20 V
Capacitance	С			2.80	pF	$V_R = 1 V$ , $f = 1 MHz$

Note: Per one device.

### **Main Characteristic**

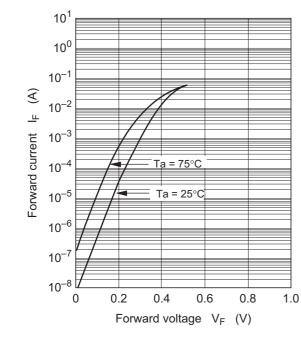


Fig.1 Forward current vs. Forward voltage

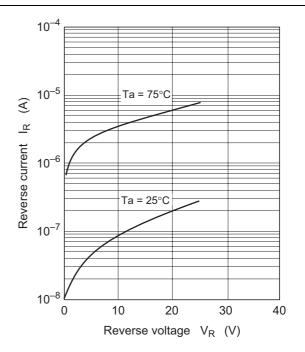


Fig.2 Reverse current vs. Reverse voltage

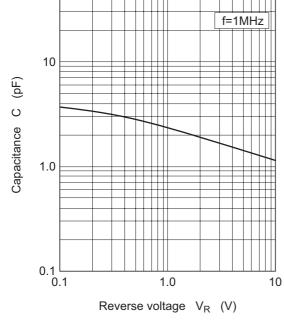
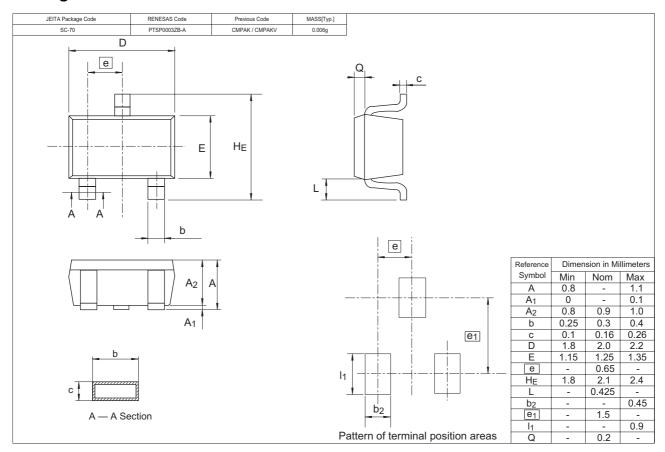


Fig.3 Capacitance vs. Reverse voltage

## **Package Dimensions**



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